

# 3D & SYSTEMS SUMMIT

## POST SHOW REPORT

3D & Systems Summit | 27 - 29 Jan 2020 | Dresden, Germany

### KEY FIGURES OF 2020 EVENT



### Executive Keynote Speeches

- **New Era for 3D**  
Jan Vardaman, President and Founder, TechSearch International, Inc.
- **Integration Technologies Transforming the World**  
Eelco Bergman, Sr. Director, Sales & Business Development, ASE Group
- **SoIC - A Longtime Game Changer**  
Dr. Douglas Yu, VP of Integrated Interconnect & Packaging, Taiwan Semiconductor Manufacturing Company Ltd.
- **3D IC Opportunities for High Performance Computing**  
Mustafa Badaroglu, Technical Director, Huawei Technologies

### Key Attending Companies

- 0eC SA
- AEMtec GmbH
- AGC Inc.
- ams AG
- Applied Materials
- ASE Group
- ASML
- AT&S AG
- Atotech Group
- BASF SE
- Berliner Glas KGaA
- Besi
- FRT GmbH
- Fujifilm Electronic Materials
- Globalfoundries
- Henkel Electronic Materials
- Hisilicon technologies
- Hitachi Chemical Europe GmbH
- Huawei
- imec
- Inphi Corp.
- INTEL
- International Test Solutions Inc.
- JTA Equipment Technology
- Siconnex customized solutions GmbH
- Siemens Healthcare GmbH
- Simco-Ion Technology Group
- Singulus Technologies AG
- SIP GmbH
- Smart Systems Hub GmbH
- SMC 'Technological Centre'
- Sony Europe B.V.
- SPEKTRA Dresden GmbH
- SPTS Technologies
- STATS ChipPAC Inc

- Brewer Science Inc
- Bruker Nano GmbH
- Bruker Nano Surfaces Division
- Carl Zeiss SMT GmbH
- CEA-LETI
- Confovis GmbH
- DECTRIS AG
- DELO Industrie Klebstoffe GmbH & Co. KGa
- DISCO HI-TEC EUROPE GmbH
- DuPont
- ERS Electronic GmbH
- ESPAT-Consulting
- ETEL SA
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- EV Group (EVG)
- Evatec AG
- Finetech GmbH & Co. KG
- Fraunhofer
- KETEK GmbH
- KLA Corporation
- Kyocera Fineceramics GmbH
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- LCP'S Engineering
- LPKF Laser & Electronics AG
- Mitsui Chemicals Europe GmbH
- Nikon Precision Europe GmbH
- Okmetic Oy
- Optim Wafer Services
- Osram Opto Semiconductors GmbH
- Panasonic Industry Europe GmbH
- Polytechnik AS
- Precitec Optronik GmbH
- RENA Technologies GmbH
- Samsung Electronics
- S-Cubed
- Sentronics Metrology GmbH
- SET Corporation SA
- STMicroelectronics
- SUSS MicroTec
- T3-Technologies
- Tessaera
- TIIInfoGroup
- Tokyo Electron Ltd
- Toray Industries Europe
- TRUMPF GmbH + Co. KG
- Trymax Semiconductor Equipment BV
- TSMC Europe
- Umicore Thin Film Products
- United Monolithic Semiconductors
- Universal Instruments Corporation
- Valeo
- Veeco GmbH
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- YXLON International GmbH

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